



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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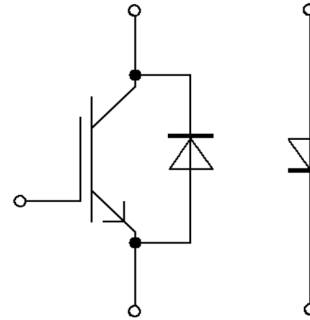
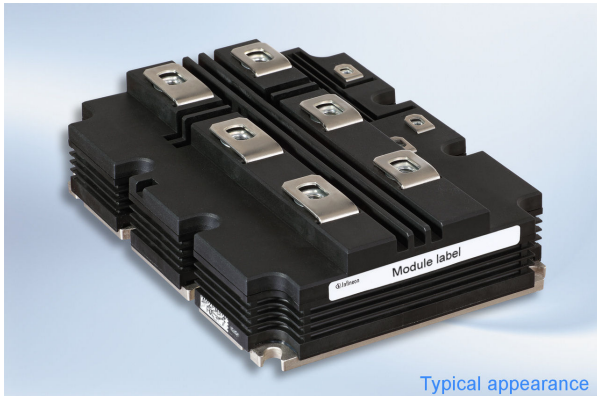
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hochisolierendes Modul mit Trench/Feldstopp IGBT3 und Emitter Controlled 3 Diode
 high insulated module with Trench/Fieldstop IGBT3 and Emitter Controlled 3 diode



$V_{CES} = 4500V$
 $I_{C\ nom} = 800A / I_{CRM} = 1600A$

Potentielle Anwendungen

- Chopper-Anwendungen
- Hochleistungsumrichter
- Mittelspannungsantriebe
- Motorantriebe
- Traktionsumrichter

Potential Applications

- Chopper applications
- High power converters
- Medium voltage converters
- Motor drives
- Traction drives

Elektrische Eigenschaften

- Große DC-Festigkeit
- Hohe dynamische Robustheit
- Hohe Kurzschlussrobustheit
- Niedriges V_{CEsat}
- Trench IGBT 3
- V_{CEsat} mit positivem Temperaturkoeffizienten

Electrical Features

- High DC stability
- High dynamic robustness
- High short-circuit capability
- Low V_{CEsat}
- Trench IGBT 3
- V_{CEsat} with positive temperature coefficient

Mechanische Eigenschaften

- AlSiC Bodenplatte für erhöhte thermische Lastwechselfestigkeit
- Gehäuse mit CTI > 600
- Gehäuse mit erweiterten Isolationseigenschaften von 10,4kV AC 10s
- Große Luft- und Kriechstrecken
- Isolierte Bodenplatte

Mechanical Features

- AlSiC base plate for increased thermal cycling capability
- Package with CTI > 600
- Package with enhanced insulation of 10.4kV AC 10s
- High creepage and clearance distances
- Isolated base plate

Module Label Code

Barcode Code 128



DMX - Code



Content of the Code

| Content of the Code | Digit |
|----------------------------|---------|
| Module Serial Number | 1 - 5 |
| Module Material Number | 6 - 11 |
| Production Order Number | 12 - 19 |
| Datecode (Production Year) | 20 - 21 |
| Datecode (Production Week) | 22 - 23 |

IGBT, Brems-Chopper / IGBT, Brake-Chopper Höchstzulässige Werte / Maximum Rated Values

| | | | | |
|--|---|-------------------|----------------------|---|
| Kollektor-Emitter-Sperrspannung Collector-emitter voltage | $T_{vj} = -40^{\circ}\text{C}$ $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ | V_{CES} | 4500 4500 4500 | V |
| Kollektor-Dauergleichstrom Continuous DC collector current | $T_C = 95^{\circ}\text{C}$, $T_{vj\max} = 125^{\circ}\text{C}$ | $I_{C\text{nom}}$ | 800 | A |
| Periodischer Kollektor-Spitzenstrom Repetitive peak collector current | $t_P = 1\text{ ms}$ | I_{CRM} | 1600 | A |
| Gate-Emitter-Spitzenspannung Gate-emitter peak voltage | | V_{GES} | +/-20 | V |

Charakteristische Werte / Characteristic Values

| | | min. | typ. | max. | | | |
|---|--|---|--------------------|--------------|--------------|--------|--------------------------------|
| Kollektor-Emitter-Sättigungsspannung Collector-emitter saturation voltage | $I_C = 800\text{ A}$, $V_{GE} = 15\text{ V}$ $I_C = 800\text{ A}$, $V_{GE} = 15\text{ V}$ | $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ | $V_{CE\text{sat}}$ | 2,50 3,10 | 2,85 3,70 | V V | |
| Gate-Schwellenspannung Gate threshold voltage | $I_C = 70,5\text{ mA}$, $V_{CE} = V_{GE}$, $T_{vj} = 25^{\circ}\text{C}$ | | V_{GEth} | 5,40 | 6,00 | 6,60 | V |
| Gateladung Gate charge | $V_{GE} = -15\text{ V} \dots +15\text{ V}$, $V_{CE} = 2800\text{ V}$ | | Q_G | 26,5 | | | μC |
| Interner Gatewiderstand Internal gate resistor | $T_{vj} = 25^{\circ}\text{C}$ | | R_{Gint} | 1,1 | | | Ω |
| Eingangskapazität Input capacitance | $f = 1\text{ MHz}$, $T_{vj} = 25^{\circ}\text{C}$, $V_{CE} = 25\text{ V}$, $V_{GE} = 0\text{ V}$ | | C_{ies} | 185 | | | nF |
| Rückwirkungskapazität Reverse transfer capacitance | $f = 1\text{ MHz}$, $T_{vj} = 25^{\circ}\text{C}$, $V_{CE} = 25\text{ V}$, $V_{GE} = 0\text{ V}$ | | C_{res} | 3,10 | | | nF |
| Kollektor-Emitter-Reststrom Collector-emitter cut-off current | $V_{CE} = 4500\text{ V}$, $V_{GE} = 0\text{ V}$, $T_{vj} = 25^{\circ}\text{C}$ | | I_{CES} | | | 5,0 | mA |
| Gate-Emitter-Reststrom Gate-emitter leakage current | $V_{CE} = 0\text{ V}$, $V_{GE} = 20\text{ V}$, $T_{vj} = 25^{\circ}\text{C}$ | | I_{GES} | | | 400 | nA |
| Einschaltverzögerungszeit, induktive Last Turn-on delay time, inductive load | $I_C = 800\text{ A}$, $V_{CE} = 2800\text{ V}$ $V_{GE} = \pm 15\text{ V}$ $R_{Gon} = 2,4\ \Omega$ | $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ | t_{don} | 0,75 0,75 | | | μs μs |
| Anstiegszeit, induktive Last Rise time, inductive load | $I_C = 800\text{ A}$, $V_{CE} = 2800\text{ V}$ $V_{GE} = \pm 15\text{ V}$ $R_{Gon} = 2,4\ \Omega$ | $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ | t_r | 0,30 0,30 | | | μs μs |
| Abschaltverzögerungszeit, induktive Last Turn-off delay time, inductive load | $I_C = 800\text{ A}$, $V_{CE} = 2800\text{ V}$ $V_{GE} = \pm 15\text{ V}$ $R_{Goff} = 7,5\ \Omega$ | $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ | t_{doff} | 6,60 6,90 | | | μs μs |
| Fallzeit, induktive Last Fall time, inductive load | $I_C = 800\text{ A}$, $V_{CE} = 2800\text{ V}$ $V_{GE} = \pm 15\text{ V}$ $R_{Goff} = 7,5\ \Omega$ | $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ | t_f | 0,35 0,45 | | | μs μs |
| Einschaltverlustenergie pro Puls Turn-on energy loss per pulse | $I_C = 800\text{ A}$, $V_{CE} = 2800\text{ V}$, $L_S = 95\text{ nH}$ $V_{GE} = \pm 15\text{ V}$, $di/dt = 3300\text{ A}/\mu\text{s}$ $R_{Gon} = 1,0\ \Omega$ | $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ | E_{on} | 3100 4100 | | | mJ mJ |
| Abschaltverlustenergie pro Puls Turn-off energy loss per pulse | $I_C = 800\text{ A}$, $V_{CE} = 2800\text{ V}$, $L_S = 95\text{ nH}$ $V_{GE} = \pm 15\text{ V}$, $du/dt = 2000\text{ V}/\mu\text{s}$ $R_{Goff} = 7,5\ \Omega$ | $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ | E_{off} | 2800 3400 | | | mJ mJ |
| Kurzschlußverhalten SC data | $V_{GE} \leq 15\text{ V}$, $V_{CC} = 2800\text{ V}$ $V_{CE\text{max}} = V_{CES} - L_{SCE} \cdot di/dt$ $t_P \leq 10\ \mu\text{s}$, $T_{vj} = 125^{\circ}\text{C}$ | | I_{SC} | 4600 | | | A |
| Wärmewiderstand, Chip bis Gehäuse Thermal resistance, junction to case | pro IGBT / per IGBT | | R_{thJC} | | | 11,1 | K/kW |
| Wärmewiderstand, Gehäuse bis Kühlkörper Thermal resistance, case to heatsink | pro IGBT / per IGBT $\lambda_{\text{Paste}} = 1\text{ W}/(\text{m}\cdot\text{K})$ / $\lambda_{\text{grease}} = 1\text{ W}/(\text{m}\cdot\text{K})$ | | R_{thCH} | | | 13,5 | K/kW |
| Temperatur im Schaltbetrieb Temperature under switching conditions | | | $T_{vj\text{op}}$ | -50 | | 125 | $^{\circ}\text{C}$ |

Diode, Brems-Chopper / Diode, Brake-Chopper

Höchstzulässige Werte / Maximum Rated Values

| | | | | |
|---|---|----------------------|----------------------|-----------------------|
| Periodische Spitzensperrspannung Repetitive peak reverse voltage | $T_{vj} = -40^{\circ}\text{C}$ $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ | V_{RRM} | 4500 4500 4500 | V |
| Dauergleichstrom Continuous DC forward current | | I_F | 800 | A |
| Periodischer Spitzenstrom Repetitive peak forward current | $t_P = 1 \text{ ms}$ | I_{FRM} | 1600 | A |
| Grenzlastintegral I^2t - value | $V_R = 0 \text{ V}$, $t_P = 10 \text{ ms}$, $T_{vj} = 125^{\circ}\text{C}$ | I^2t | 255 | kA^2s |
| Spitzenverlustleistung Maximum power dissipation | $T_{vj} = 125^{\circ}\text{C}$ | P_{RQM} | 1600 | kW |
| Mindesteinschaltdauer Minimum turn-on time | | $t_{on \text{ min}}$ | 10,0 | μs |

Charakteristische Werte / Characteristic Values

| | | | min. | typ. | max. | |
|---|---|---|---------------------|--------------|--------------|--------------------------------|
| Durchlassspannung Forward voltage | $I_F = 800 \text{ A}$, $V_{GE} = 0 \text{ V}$ $I_F = 800 \text{ A}$, $V_{GE} = 0 \text{ V}$ | $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ | V_F | 2,50 2,50 | 3,10 3,00 | V V |
| Rückstromspitze Peak reverse recovery current | $I_F = 800 \text{ A}$, $-di_F/dt = 3300 \text{ A}/\mu\text{s}$ ($T_{vj}=125^{\circ}\text{C}$) $V_R = 2800 \text{ V}$ $V_{GE} = -15 \text{ V}$ | $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ | I_{RM} | 1000 1150 | | A A |
| Sperrverzögerungsladung Recovered charge | $I_F = 800 \text{ A}$, $-di_F/dt = 3300 \text{ A}/\mu\text{s}$ ($T_{vj}=125^{\circ}\text{C}$) $V_R = 2800 \text{ V}$ $V_{GE} = -15 \text{ V}$ | $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ | Q_r | 770 1400 | | μC μC |
| Abschaltenergie pro Puls Reverse recovery energy | $I_F = 800 \text{ A}$, $-di_F/dt = 3300 \text{ A}/\mu\text{s}$ ($T_{vj}=125^{\circ}\text{C}$) $V_R = 2800 \text{ V}$ $V_{GE} = -15 \text{ V}$ | $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ | E_{rec} | 1200 2400 | | mJ mJ |
| Wärmewiderstand, Chip bis Gehäuse Thermal resistance, junction to case | pro Diode / per diode | | R_{thJC} | | 25,5 | K/kW |
| Wärmewiderstand, Gehäuse bis Kühlkörper Thermal resistance, case to heatsink | pro Diode / per diode $\lambda_{\text{Paste}} = 1 \text{ W}/(\text{m}\cdot\text{K})$ / $\lambda_{\text{grease}} = 1 \text{ W}/(\text{m}\cdot\text{K})$ | | R_{thCH} | 21,0 | | K/kW |
| Temperatur im Schaltbetrieb Temperature under switching conditions | | | $T_{vj \text{ op}}$ | -50 | 125 | $^{\circ}\text{C}$ |

Diode, Revers / Diode, Reverse

Höchstzulässige Werte / Maximum Rated Values

| | | | | |
|---|---|----------------------|----------------------|-----------------------|
| Periodische Spitzensperrspannung Repetitive peak reverse voltage | $T_{vj} = -40^{\circ}\text{C}$ $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ | V_{RRM} | 4500 4500 4500 | V |
| Dauergleichstrom Continuous DC forward current | | I_F | 800 | A |
| Periodischer Spitzenstrom Repetitive peak forward current | $t_P = 1 \text{ ms}$ | I_{FRM} | 1600 | A |
| Grenzlastintegral I^2t - value | $V_R = 0 \text{ V}$, $t_P = 10 \text{ ms}$, $T_{vj} = 125^{\circ}\text{C}$ | I^2t | 255 | kA^2s |
| Spitzenverlustleistung Maximum power dissipation | $T_{vj} = 125^{\circ}\text{C}$ | P_{RQM} | 1600 | kW |
| Mindesteinschaltdauer Minimum turn-on time | | $t_{on \text{ min}}$ | 10,0 | μs |

Charakteristische Werte / Characteristic Values

| | | | min. | typ. | max. | |
|---|---|---|---------------------|--------------|--------------|--------------------------------|
| Durchlassspannung Forward voltage | $I_F = 800 \text{ A}$, $V_{GE} = 0 \text{ V}$ $I_F = 800 \text{ A}$, $V_{GE} = 0 \text{ V}$ | $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ | V_F | 2,50 2,50 | 3,10 3,00 | V V |
| Rückstromspitze Peak reverse recovery current | $I_F = 800 \text{ A}$, $-di_F/dt = 3300 \text{ A}/\mu\text{s}$ ($T_{vj}=125^{\circ}\text{C}$) $V_R = 2800 \text{ V}$ $V_{GE} = -15 \text{ V}$ | $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ | I_{RM} | 1000 1150 | | A A |
| Sperrverzögerungsladung Recovered charge | $I_F = 800 \text{ A}$, $-di_F/dt = 3300 \text{ A}/\mu\text{s}$ ($T_{vj}=125^{\circ}\text{C}$) $V_R = 2800 \text{ V}$ $V_{GE} = -15 \text{ V}$ | $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ | Q_r | 770 1400 | | μC μC |
| Abschaltenergie pro Puls Reverse recovery energy | $I_F = 800 \text{ A}$, $-di_F/dt = 3300 \text{ A}/\mu\text{s}$ ($T_{vj}=125^{\circ}\text{C}$) $V_R = 2800 \text{ V}$ $V_{GE} = -15 \text{ V}$ | $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ | E_{rec} | 1200 2400 | | mJ mJ |
| Wärmewiderstand, Chip bis Gehäuse Thermal resistance, junction to case | pro Diode / per diode | | R_{thJC} | | 25,5 | K/kW |
| Wärmewiderstand, Gehäuse bis Kühlkörper Thermal resistance, case to heatsink | pro Diode / per diode $\lambda_{\text{Paste}} = 1 \text{ W}/(\text{m}\cdot\text{K})$ / $\lambda_{\text{grease}} = 1 \text{ W}/(\text{m}\cdot\text{K})$ | | R_{thCH} | | 21,0 | K/kW |
| Temperatur im Schaltbetrieb Temperature under switching conditions | | | $T_{vj \text{ op}}$ | -50 | 125 | $^{\circ}\text{C}$ |

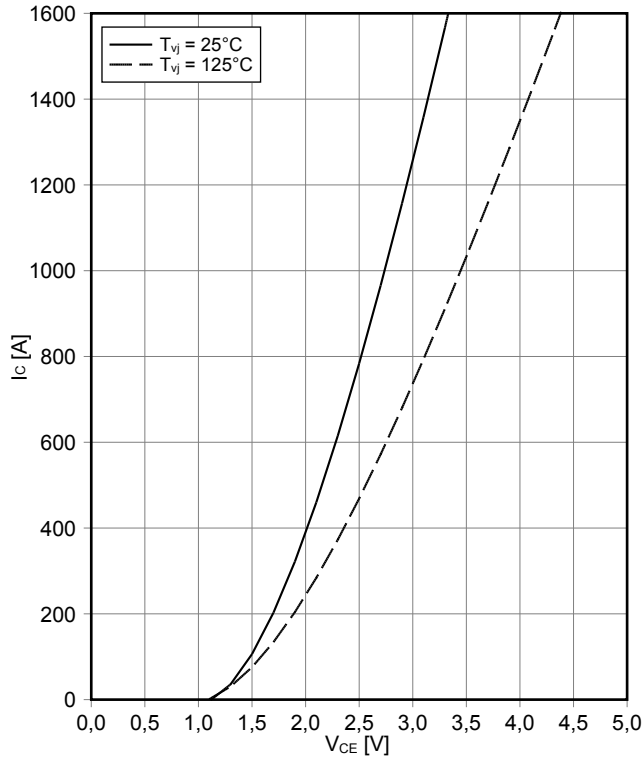
Modul / Module

| | | | | | |
|---|--|--|--------------|--------------|--------------|
| Isolations-Prüfspannung Isolation test voltage | RMS, f = 50 Hz, t = 10 s | V _{ISOL} | 10,4 | | kV |
| Teilentladungs-Aussetzspannung Partial discharge extinction voltage | RMS, f = 50 Hz, Q _{PD} ≤ 10 pC | V _{ISOL} | 3,5 | | kV |
| Kollektor-Emitter-Gleichsperrspannung DC stability | T _{vj} = 25°C, 100 fit | V _{CE D} | 3000 | | V |
| Material Modulgrundplatte Material of module baseplate | | | AlSiC | | |
| Innere Isolation Internal isolation | Basisisolierung (Schutzklasse 1, EN61140) basic insulation (class 1, IEC 61140) | | AlN | | |
| Kriechstrecke Creepage distance | Kontakt - Kühlkörper / terminal to heatsink Kontakt - Kontakt / terminal to terminal | | 56,0 56,0 | | mm |
| Luftstrecke Clearance | Kontakt - Kühlkörper / terminal to heatsink Kontakt - Kontakt / terminal to terminal | | 26,0 26,0 | | mm |
| Vergleichszahl der Kriechwegbildung Comperative tracking index | | CTI | > 600 | | |
| | | | min. | typ. | max. |
| Modulstreuinduktivität Stray inductance module | | L _{sCE} | | 20 | nH |
| Modulleitungswiderstand, Anschlüsse - Chip Module lead resistance, terminals - chip | T _c = 25°C, pro Schalter / per switch | R _{CC'+EE'} R _{AA'+CC'} | | 0,18 0,18 | mΩ |
| Lagertemperatur Storage temperature | | T _{stg} | -55 | | 125 °C |
| Anzugsdrehmoment f. Modulmontage Mounting torque for modul mounting | Schraube M6 - Montage gem. gültiger Applikationsschrift Screw M6 - Mounting according to valid application note | M | 4,25 | | 5,75 Nm |
| Anzugsdrehmoment f. elektr. Anschlüsse Terminal connection torque | Schraube M4 - Montage gem. gültiger Applikationsschrift Screw M4 - Mounting according to valid application note Schraube M8 - Montage gem. gültiger Applikationsschrift Screw M8 - Mounting according to valid application note | M | 1,8 8,0 | - - | 2,1 10 Nm |
| Gewicht Weight | | G | | 1400 | g |

Das maximal zulässige du/dt, definiert zwischen 0,6 und 1×V_{ce}, beträgt 2400V/μs.
The maximum allowed dv/dt measured between 0,6 and 1×V_{ce} is 2400V/μs.

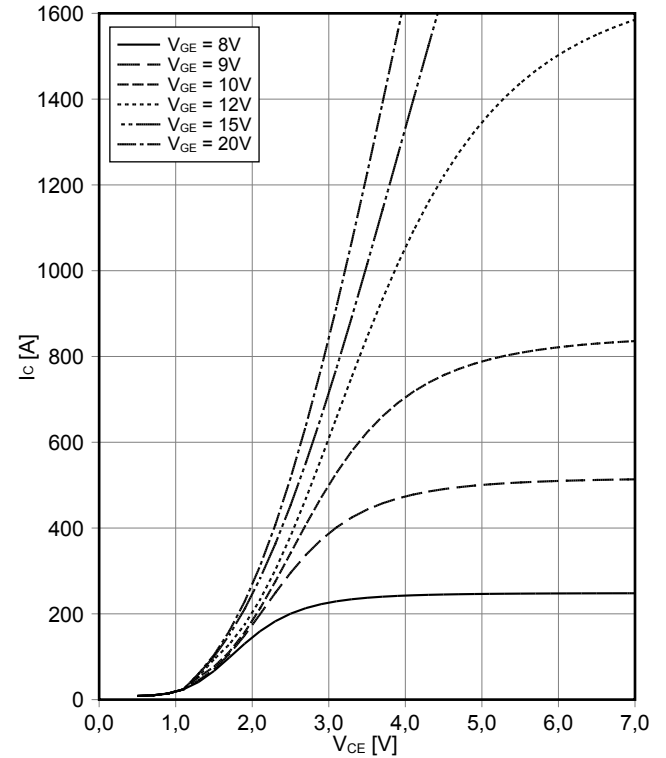
Ausgangskennlinie IGBT, Brems-Chopper (typisch)
output characteristic IGBT, Brake-Chopper (typical)

$I_C = f(V_{CE})$
 $V_{GE} = 15\text{ V}$



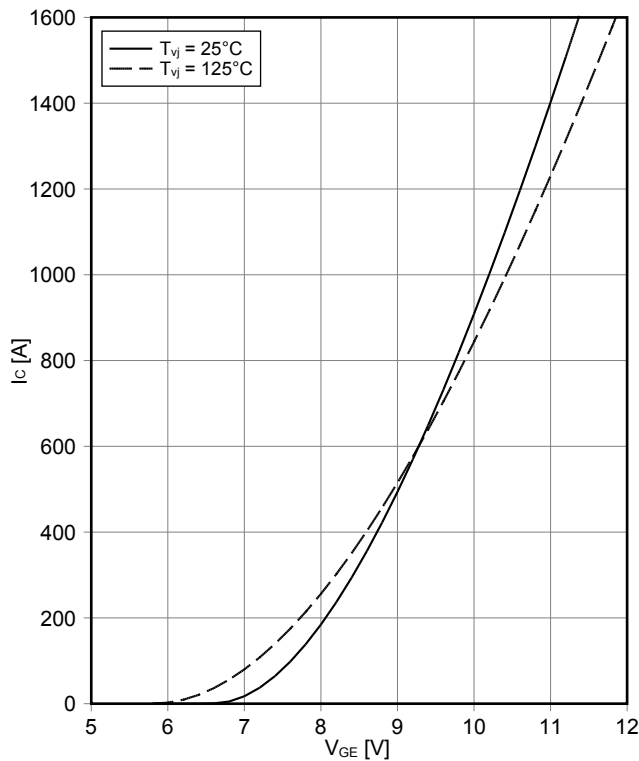
Ausgangskennlinienfeld IGBT, Brems-Chopper (typisch)
output characteristic IGBT, Brake-Chopper (typical)

$I_C = f(V_{CE})$
 $T_{vj} = 125^\circ\text{C}$



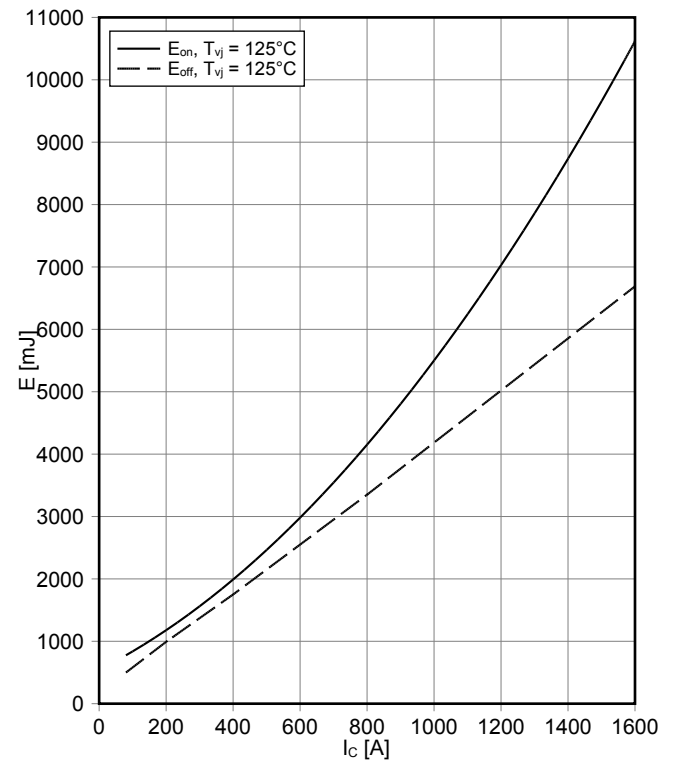
Übertragungscharakteristik IGBT, Brems-Chopper (typisch)
transfer characteristic IGBT, Brake-Chopper (typical)

$I_C = f(V_{GE})$
 $V_{CE} = 20\text{ V}$



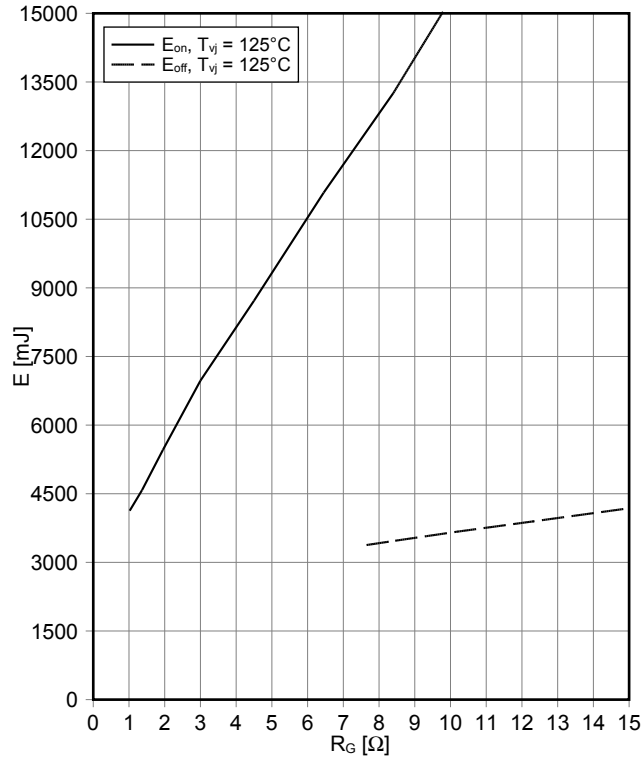
Schaltverluste IGBT, Brems-Chopper (typisch)
switching losses IGBT, Brake-Chopper (typical)

$E_{on} = f(I_C)$, $E_{off} = f(I_C)$
 $V_{GE} = \pm 15\text{ V}$, $R_{Gon} = 1\ \Omega$, $R_{Goff} = 7.5\ \Omega$, $V_{CE} = 2800\text{ V}$



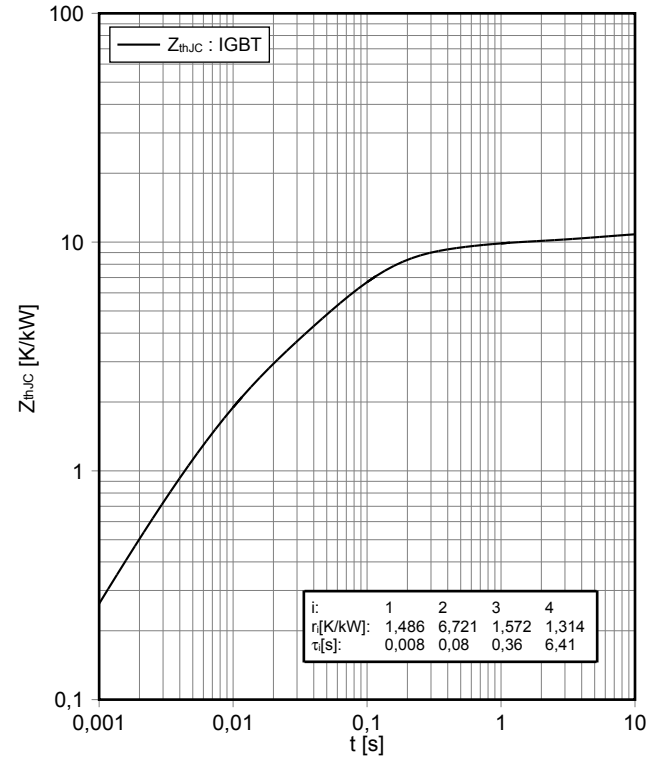
Schaltverluste IGBT, Brems-Chopper (typisch) switching losses IGBT, Brake-Chopper (typical)

$E_{on} = f(R_G), E_{off} = f(R_G)$
 $V_{GE} = \pm 15 \text{ V}, I_C = 800 \text{ A}, V_{CE} = 2800 \text{ V}$



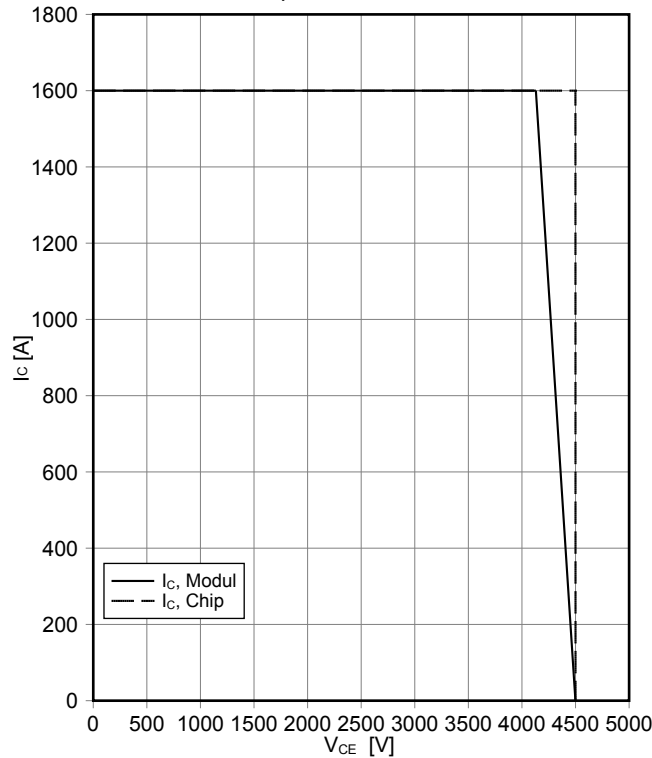
Transienter Wärmewiderstand IGBT, Brems-Chopper transient thermal impedance IGBT, Brake-Chopper

$Z_{thJC} = f(t)$



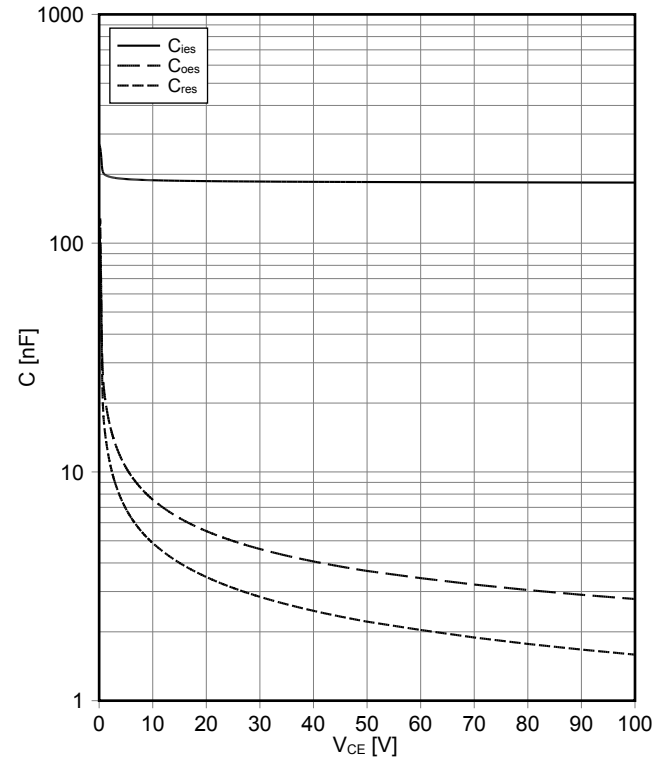
Sicherer Rückw.-Arbeitsber. IGBT, Brems-Chopper (RBSOA) reverse bias safe operating area IGBT, Brake-Chopper (RBSOA)

$I_C = f(V_{CE})$
 $V_{GE} = \pm 15 \text{ V}, R_{Goff} = 7.5 \Omega, T_{vj} = 125^\circ\text{C}$



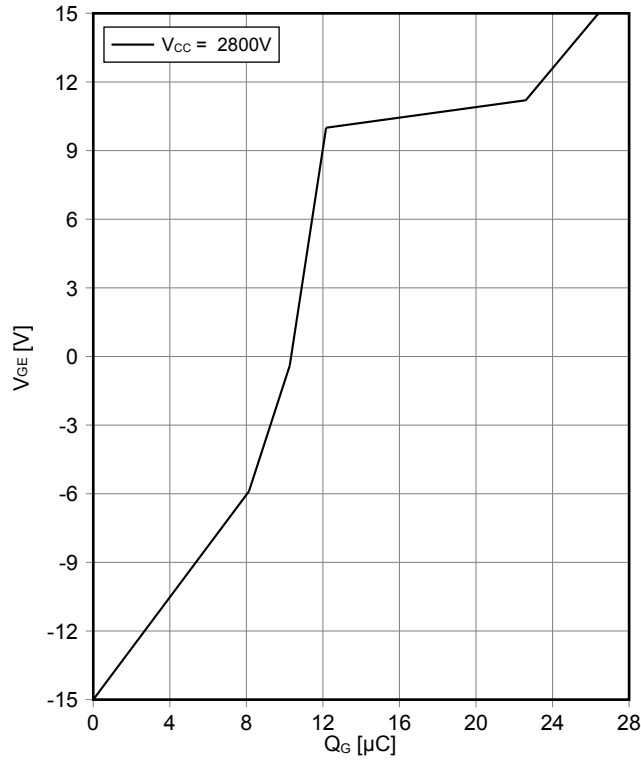
Kapazitäts Charakteristik IGBT, Brems-Chopper (typisch) capacity characteristic IGBT, Brake-Chopper (typical)

$C = f(V_{CE})$
 $V_{GE} = 0 \text{ V}, T_{vj} = 25^\circ\text{C}, f = 1 \text{ MHz}$



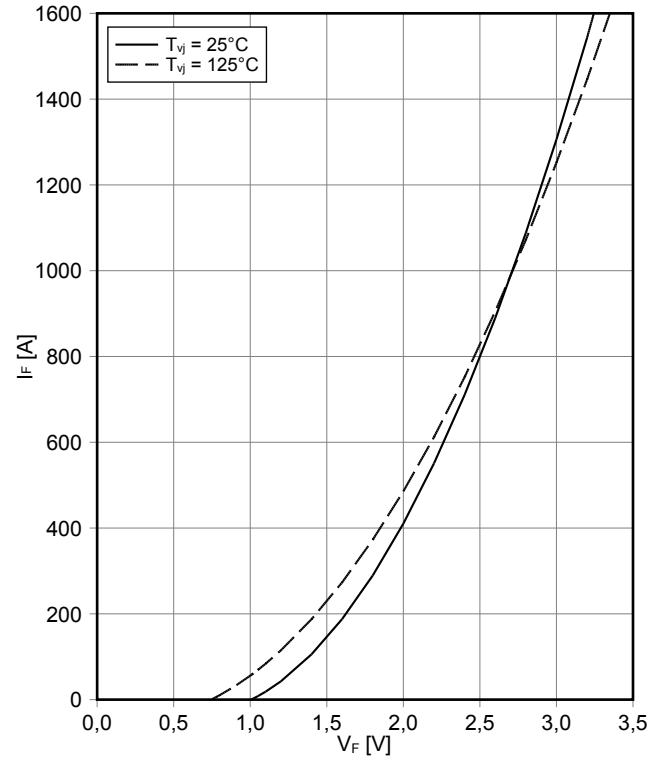
Gateladungs Charakteristik IGBT, Brems-Chopper (typisch)
gate charge characteristic IGBT, Brake-Chopper (typical)

$V_{GE} = f(Q_G)$
 $I_C = 800 \text{ A}, T_{vj} = 25^\circ\text{C}$



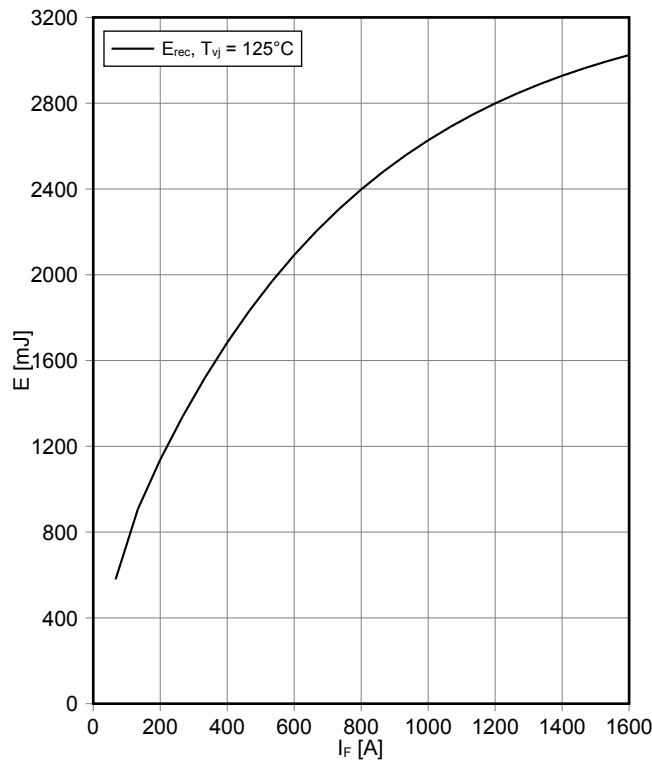
Durchlasskennlinie der Diode, Brems-Chopper (typisch)
forward characteristic of Diode, Brake-Chopper (typical)

$I_F = f(V_F)$



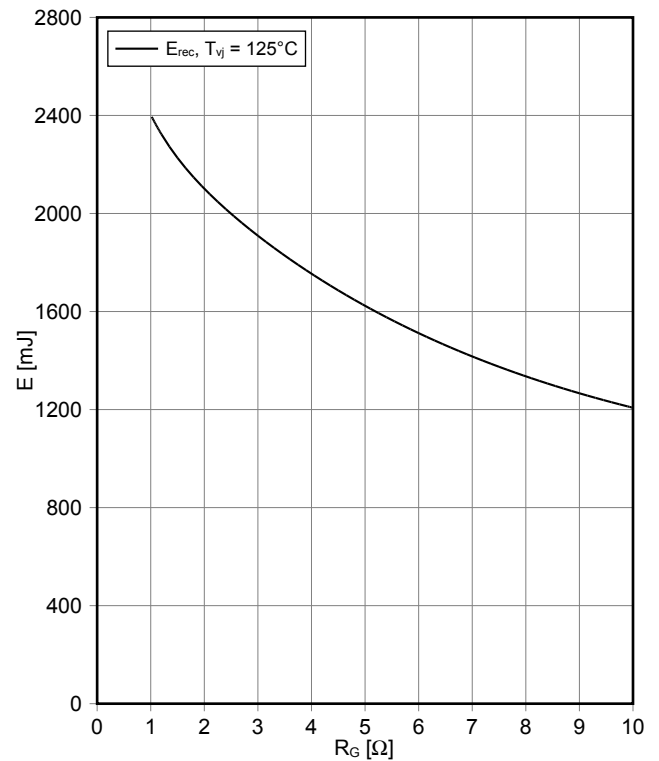
Schaltverluste Diode, Brems-Chopper (typisch)
switching losses Diode, Brake-Chopper (typical)

$E_{rec} = f(I_F)$
 $-di_F/dt = 3300 \text{ A}/\mu\text{s}, V_{CE} = 2800 \text{ V}$

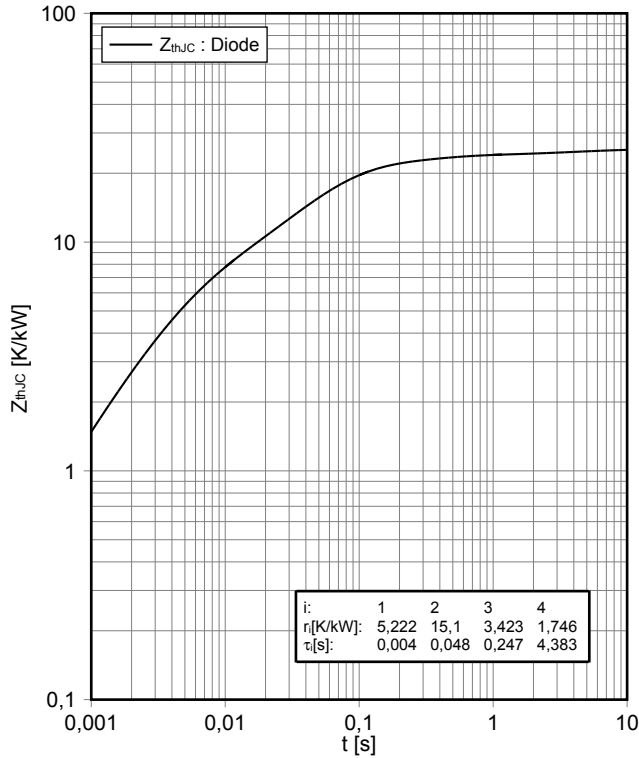


Schaltverluste Diode, Brems-Chopper (typisch)
switching losses Diode, Brake-Chopper (typical)

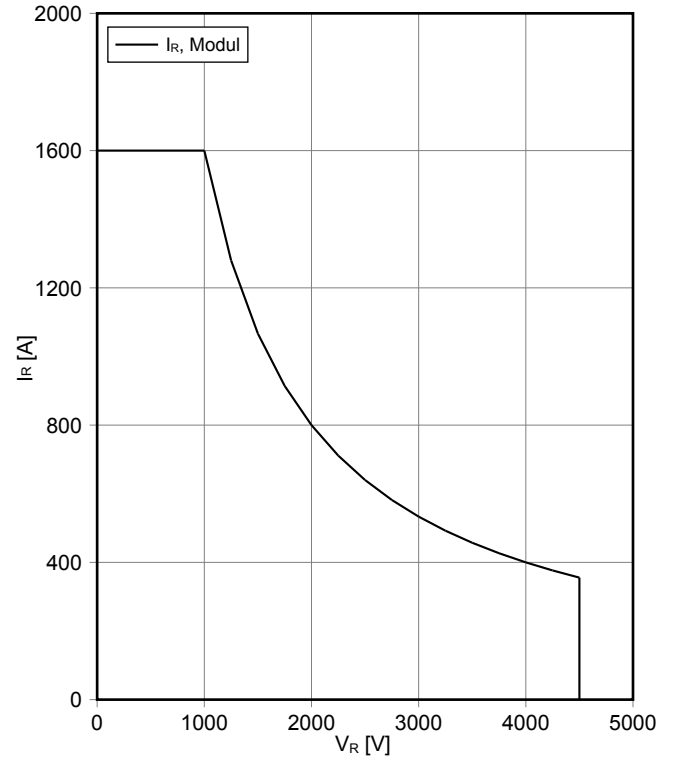
$E_{rec} = f(R_G)$
 $I_F = 800 \text{ A}, V_{CE} = 2800 \text{ V}$



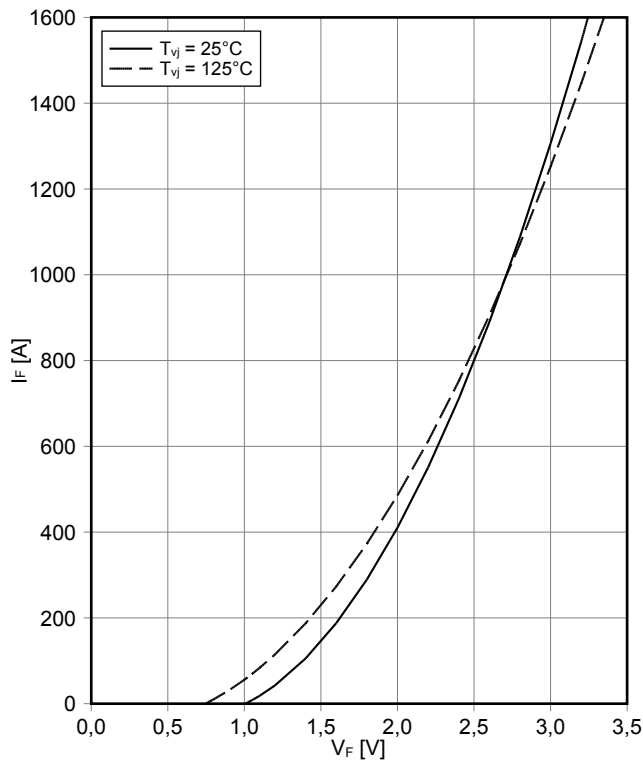
Transienter Wärmewiderstand Diode, Brems-Chopper
transient thermal impedance Diode, Brake-Chopper
 $Z_{thJC} = f(t)$



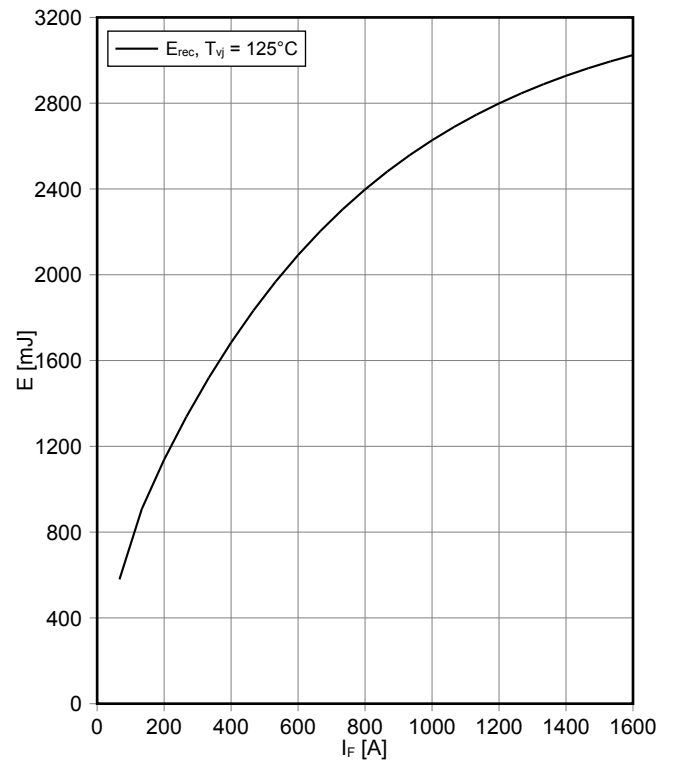
Sicherer Arbeitsbereich Diode, Brems-Chopper (SOA)
safe operation area Diode, Brake-Chopper (SOA)
 $I_R = f(V_R)$
 $T_{vj} = 125^\circ\text{C}$



Durchlasskennlinie der Diode, Revers (typisch)
forward characteristic of Diode, Reverse (typical)
 $I_F = f(V_F)$

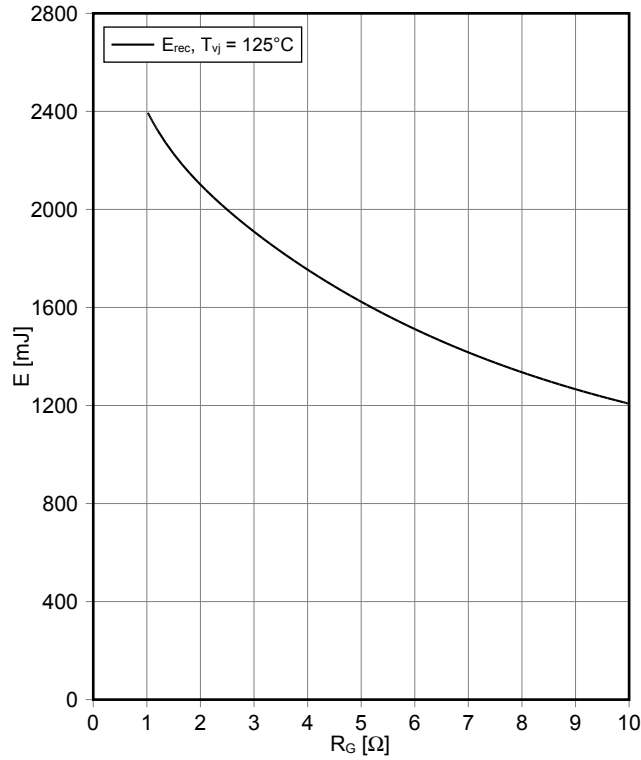


Schaltverluste Diode, Revers (typisch)
switching losses Diode, Reverse (typical)
 $E_{rec} = f(I_F)$
 $-di_F/dt = 3300\text{A}/\mu\text{s}$, $V_{CE} = 2800\text{V}$



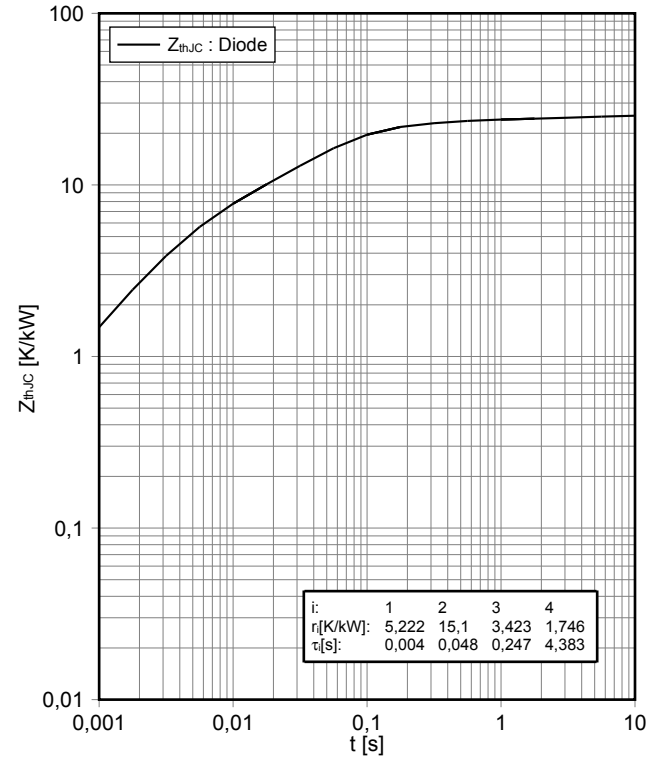
Schaltverluste Diode, Revers (typisch)
switching losses Diode, Reverse (typical)

$E_{rec} = f(R_G)$
 $I_F = 800 \text{ A}, V_{CE} = 2800 \text{ V}$



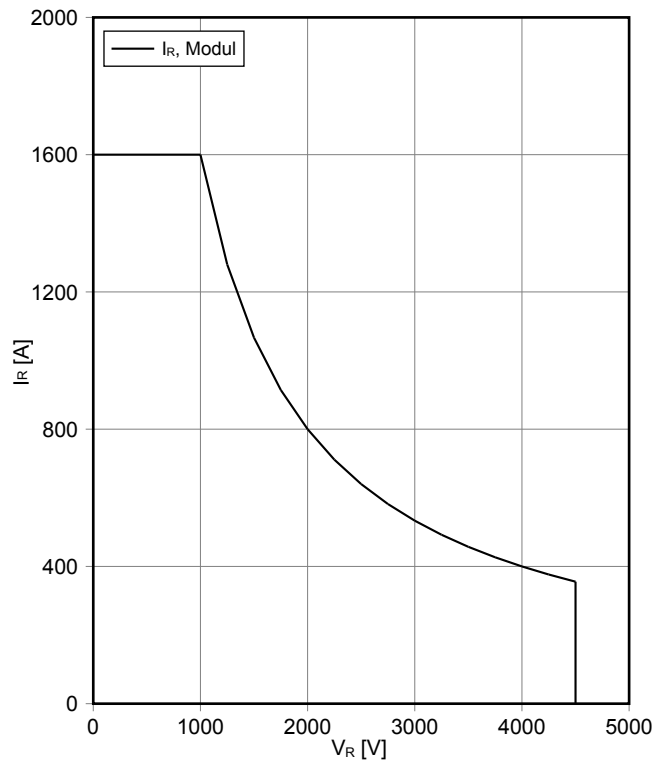
Transienter Wärmewiderstand Diode, Revers
transient thermal impedance Diode, Reverse

$Z_{thJC} = f(t)$

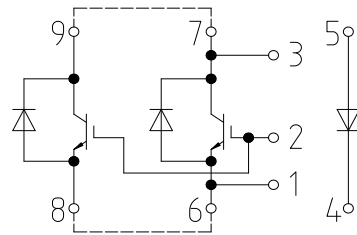


Sicherer Arbeitsbereich Diode, Revers (SOA)
safe operation area Diode, Reverse (SOA)

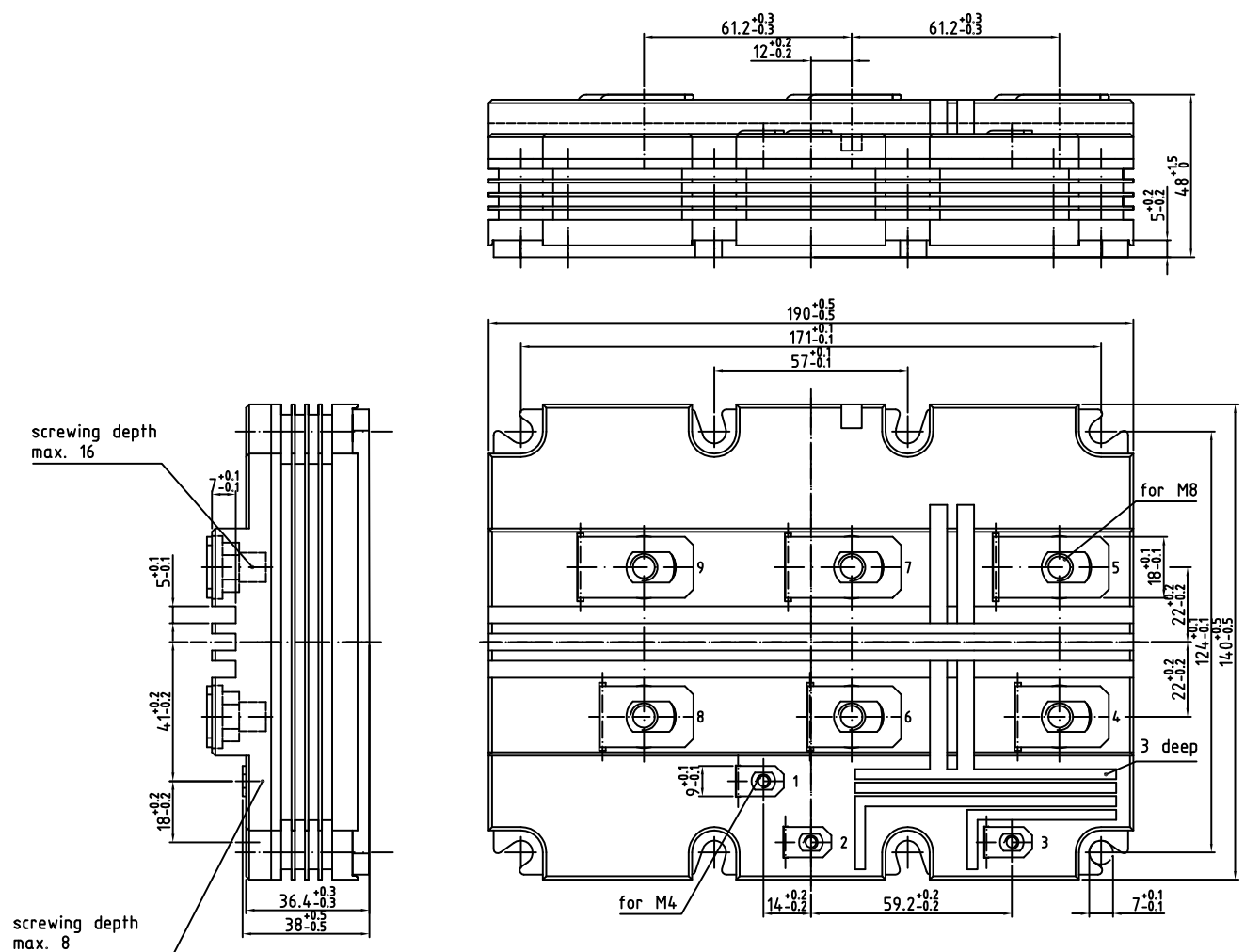
$I_R = f(V_R)$
 $T_{vj} = 125^\circ\text{C}$



Schaltplan / Circuit diagram



Gehäuseabmessungen / Package outlines



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